

ABSTRACT

A semiconductor device comprising a substrate (10). An interconnect pattern (12) is formed over the substrate (10), and the substrate (10) has a first portion (14) and a second portion (16) to be superposed on the first portion (14). The first portion (14) has edges (22), (24), (26) and (28) as positioning references. The second portion (16) has a shape to be superposed over the first portion (14) except the edges (22), (24), (26) and (28).

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